

N-Ch MOSFET

General Description

The WSF25N20 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF25N20 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

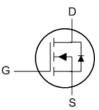
BV _{DSS}	R _{DSON}	I _D
200V	60mΩ	25A

Applications

- High Frequency Point-of-Load Synchronous
 Buck Converter
- Networking DC-DC Power System
- Load Switch

TO-252 Pin Configuration





Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	200	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	25	A
I₀@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	16	A
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	3.7	A
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	3.0	A
I _{DM}	Pulsed Drain Current ²	75	A
EAS	Single Pulse Avalanche Energy ³	35	mJ
I _{AS}	Avalanche Current	6.5	A
P₀@T _C =25℃	Total Power Dissipation ³	113	W
P₀@Tc=100℃	Total Power Dissipation ³	45	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		50	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		1.1	℃ /W

Absolute Maximum Ratings



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Electrical Characteristics (T_J=25¹C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage V _{GS} =0V , I _D =250uA		200			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.098		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =12A		60	75	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =6.0V , I _D =10A		85	150	mΩ
V _{GS(th)}	Gate Threshold Voltage		2.0	3.0	4.0	V
	V _{GS(th)} Temperature Coefficient	— V _{GS} =V _{DS} , I _D =250uA		-4.57		mV/°C
	Drain Source Lookage Current	V _{DS} =160V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =160V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm25V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =8A		20		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2	4	Ω
Qg	Total Gate Charge (10V)			40		
Q _{gs}	Gate-Source Charge	V_{DS} =100V , V_{GS} =10V , I_D =12A		14		nC
Q _{gd}	Gate-Drain Charge			10		
T _{d(on)}	Turn-On Delay Time			16		
Tr	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =6 Ω ,		7		
T _{d(off)}	Turn-Off Delay Time	I _D =12Α, R∟=30Ω		37		ns
T _f	Fall Time			15		
Ciss	Input Capacitance			2350		
C _{oss}	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		155		pF
C _{rss}	Reverse Transfer Capacitance			45		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	V _{DD} =25V , L=0.5mH , I _{AS} =6.5A	10			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			12	А
I _{SM}	Pulsed Source Current ^{2,6}	$v_{\rm G}$ - $v_{\rm D}$ - $0v$, Force Current			36	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =12A , TJ=25℃			1.3	V
t _{rr}	Reverse Recovery Time			75		nS
Q _{rr}	Reverse Recovery Charge	IF=12A , dl/dt=100A/ μs , T _J =25 $^\circ C$		250		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<=10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V,L=0.5mH,I_{AS}=6.5A

4. The power dissipation is limited by 150 °C junction temperature

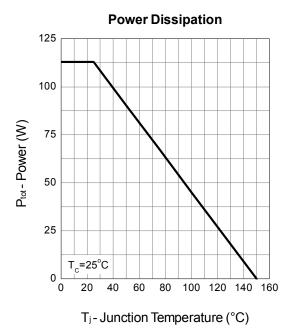
5. The Min. value is 100% EAS tested guarantee.

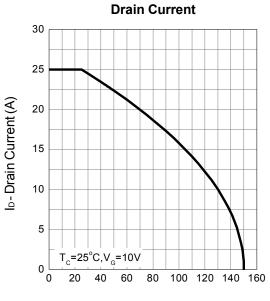
6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



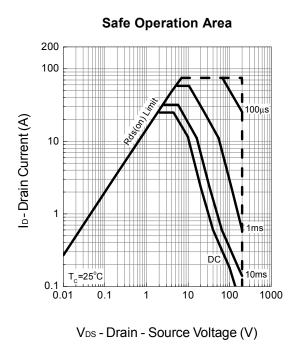
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Typical Characteristics

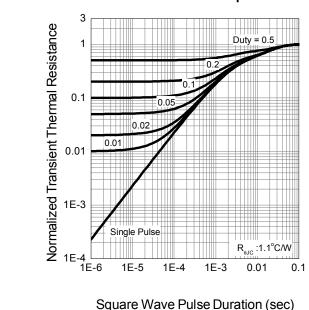




T_j-Junction Temperature



Thermal Transient Impedance

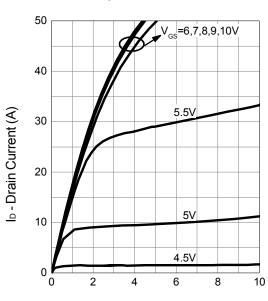


Square Wave Pulse Duration (sec)

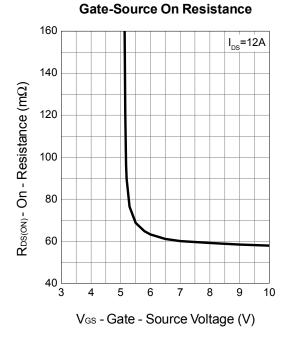


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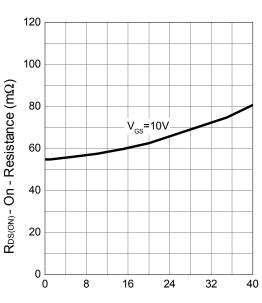
Typical Characteristics



VDS-Drain - Source Voltage (V)



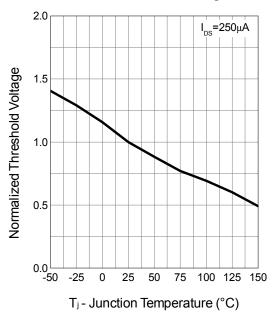
Output Characteristics



Drain-Source On Resistance

ID-Drain Current (A)

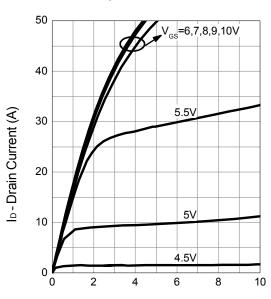
Gate Threshold Voltage



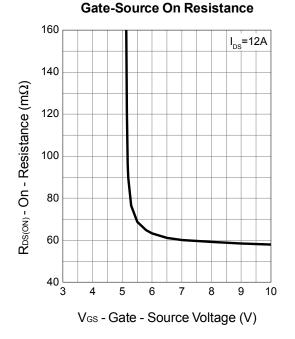


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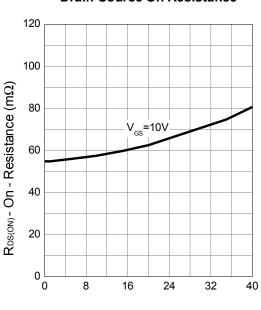
Typical Characteristics



VDS-Drain - Source Voltage (V)



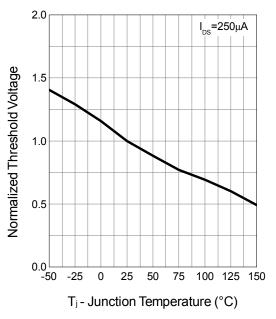
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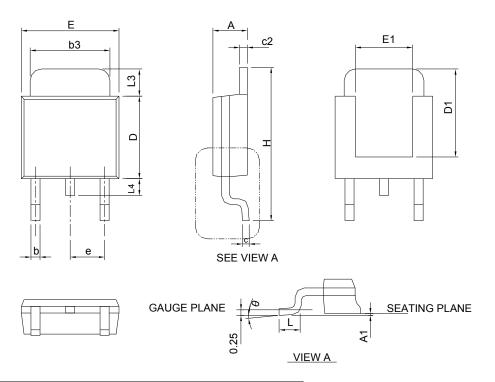




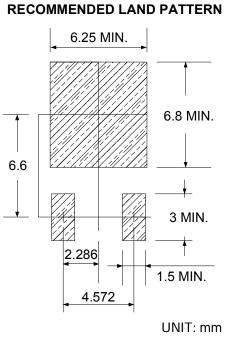


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TO-252 Package Information



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s>-⊠mo_	MILLIM	ETERS	INC	HES
Ľ	MIN.	MAX.	MIN.	MAX.
А	2.18	2.39	0.086	0.094
A1	-	0.13	-	0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
с	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
Е	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
е	2.29 BSC		0.09) BSC
Н	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4	-	1.02	-	0.040
θ	0°	8°	0°	8°





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